

N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^d	Q_g (Typ.)
60	0.0065 at $V_{GS} = 10$ V	18	13.5 nC
	0.0085 at $V_{GS} = 4.5$ V		

FEATURES

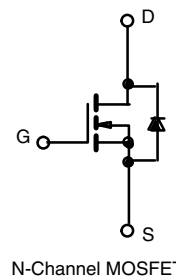
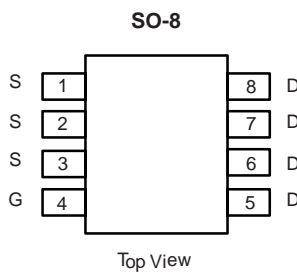
- DT-Trench Power MOSFET
- 100 % R_g and UIS tested

APPLICATIONS

- DC/DC converters
- Power supplies
- Motor drive control
- Battery and load switch



RoHS
COMPLIANT



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	60	V
Gate-source voltage	V_{GS}	± 20	
Continuous drain current ($T_J = 150$ °C)	I_D	$T_C = 25$ °C	A
		$T_C = 70$ °C	
		$T_A = 25$ °C	
		$T_A = 70$ °C	
Pulsed drain current ($t = 100$ μ s)	I_{DM}	72	A
Continuous source-drain diode current	I_S	$T_C = 25$ °C	
		$T_A = 25$ °C	
Single pulse avalanche current	I_{AS}	70	mJ
Single pulse avalanche energy	E_{AS}	90	
Maximum power dissipation	P_D	$T_C = 25$ °C	W
		$T_C = 70$ °C	
		$T_A = 25$ °C	
		$T_A = 70$ °C	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^c		260	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^a	$t \leq 10$ s	R_{thJA}	30	50	°C/W
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	18	25	

Notes

- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- Maximum under steady state conditions is 85 °C/W

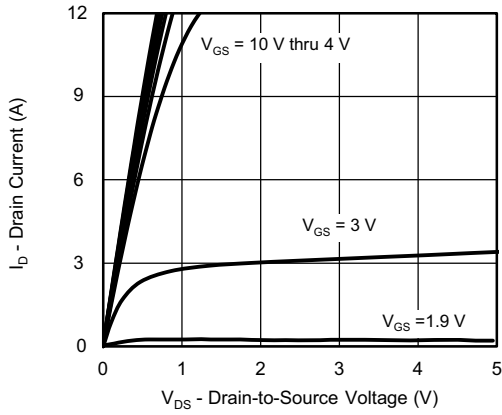
SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$	-	33	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	-4.8	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1	-	3	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
		$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}, T_J = 70\text{ }^\circ\text{C}$	-	-	10	
On-state drain current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	12	-	-	
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$	-	0.0065	0.0080	Ω
		$V_{GS} = 4.5\text{ V}, I_D = 5\text{ A}$	-	0.0085	0.0110	
Forward transconductance ^a	g_{fs}	$V_{DS} = 10\text{ V}, I_D = 10\text{ A}$	-	39	-	S
Dynamic ^b						
Input capacitance	C_{ISS}	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	4090	-	pF
Output capacitance	C_{OSS}		-	1030	-	
Reverse transfer capacitance	C_{RSS}		-	75	-	
Total gate charge	Q_g	$V_{DS} = 48\text{ V}, V_{GS} = 10\text{ V}, I_D = 5\text{ A}$	-	13.5	-	nC
		$V_{DS} = 48\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 5\text{ A}$	-	7.4	-	
Gate-source charge	Q_{gs}	$V_{DS} = 48\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 5\text{ A}$	-	3.9	-	nC
Gate-drain charge	Q_{gd}		-	2.1	-	
Gate resistance	R_g		$f = 1\text{ MHz}$	-	3	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 48\text{ V}, R_L = 6\text{ }\Omega, I_D \cong 5\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	-	8	-	ns
Rise time	t_r		-	22	-	
Turn-off delay time	$t_{d(off)}$		-	11	-	
Fall time	t_f		-	10	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 48\text{ V}, R_L = 6\text{ }\Omega, I_D \cong 5\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$	-	14	-	
Rise time	t_r		-	27	-	
Turn-off delay time	$t_{d(off)}$		-	11	-	
Fall time	t_f		-	24	-	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	18	A
Pulse diode forward current	I_{SM}		-	-	72	
Body diode voltage	V_{SD}	$I_S = 5\text{ A}, V_{GS} = 0\text{ V}$	-	0.70	1.2	V
Body diode reverse recovery time	t_{rr}	$I_F = 5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$	-	30	62	ns
Body diode reverse recovery charge	Q_{rr}		-	60	125	nC
Reverse recovery fall time	t_a		-	15	-	ns
Reverse recovery rise time	t_b		-	15	-	

Notes

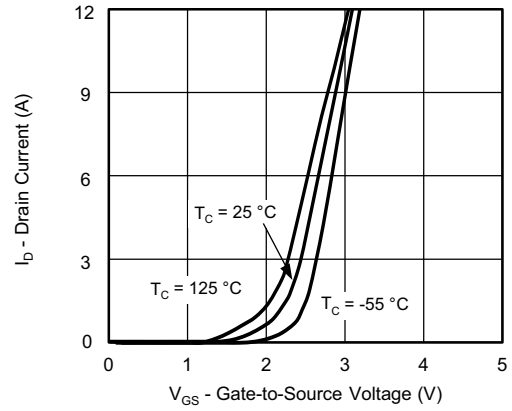
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
 b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

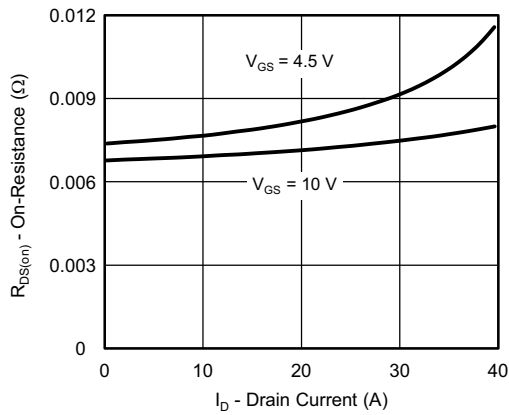
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



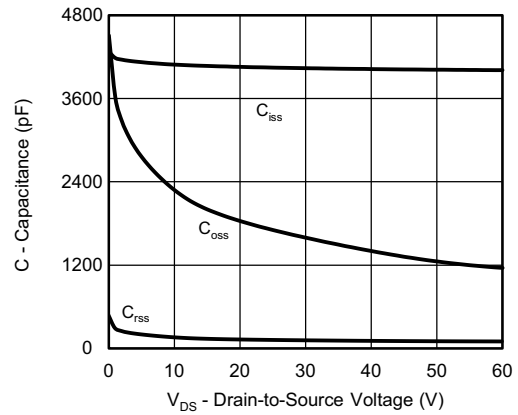
Output Characteristics



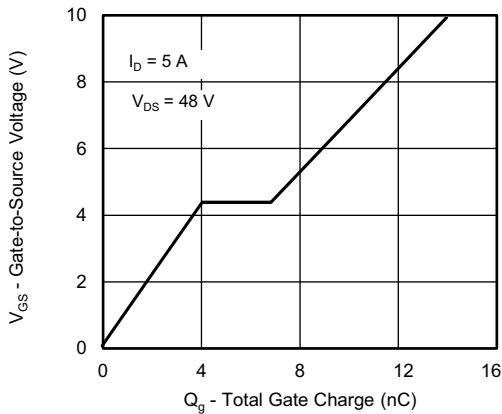
Transfer Characteristics



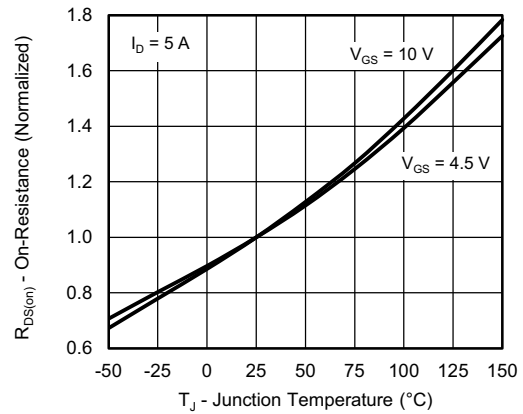
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

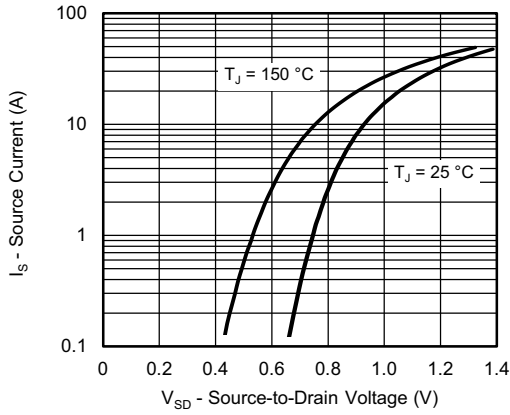


Gate Charge

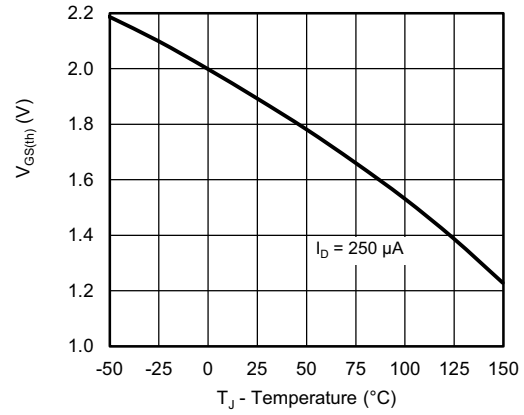


On-Resistance vs. Junction Temperature

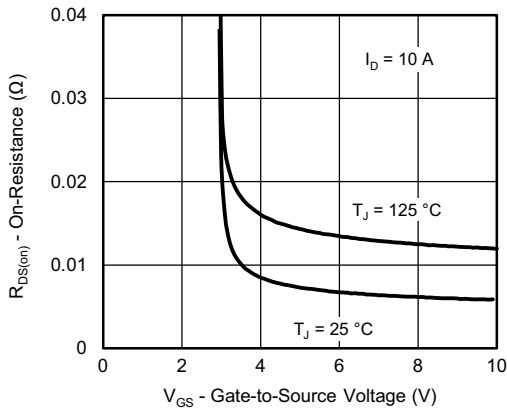
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



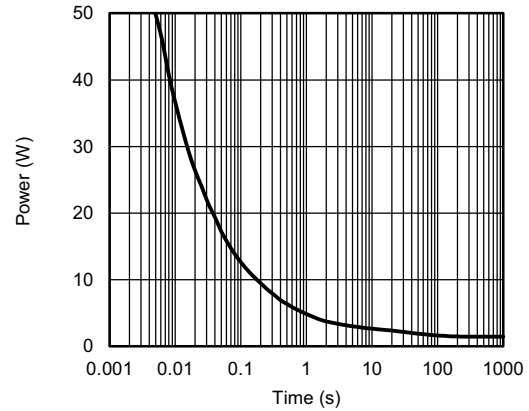
Source-Drain Diode Forward Voltage



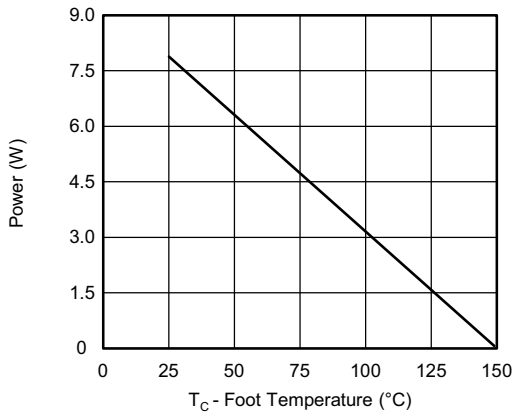
Threshold Voltage



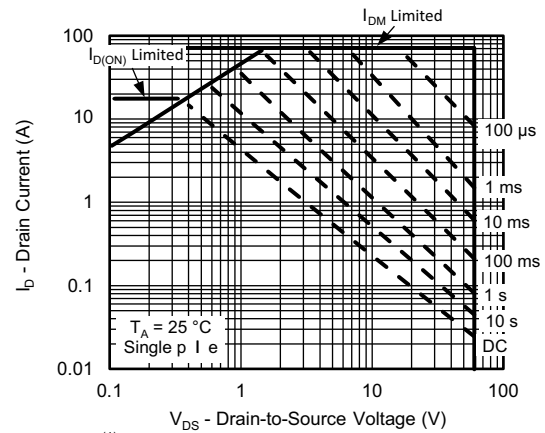
On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Power, Junction-to-Foot

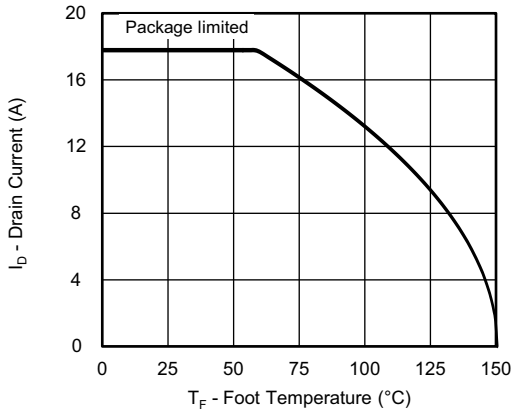


(1) $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

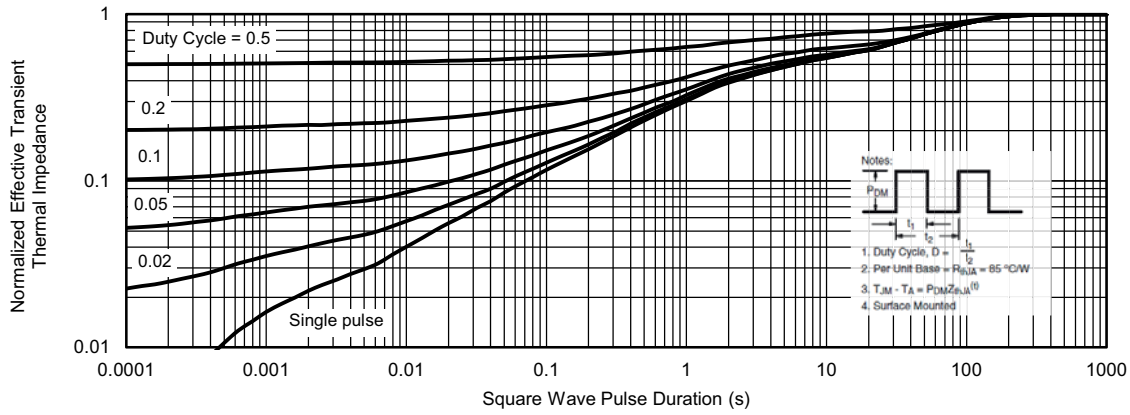
Safe Operating Area, Junction-to-Ambient

Limited by $R_{DS(on)}$

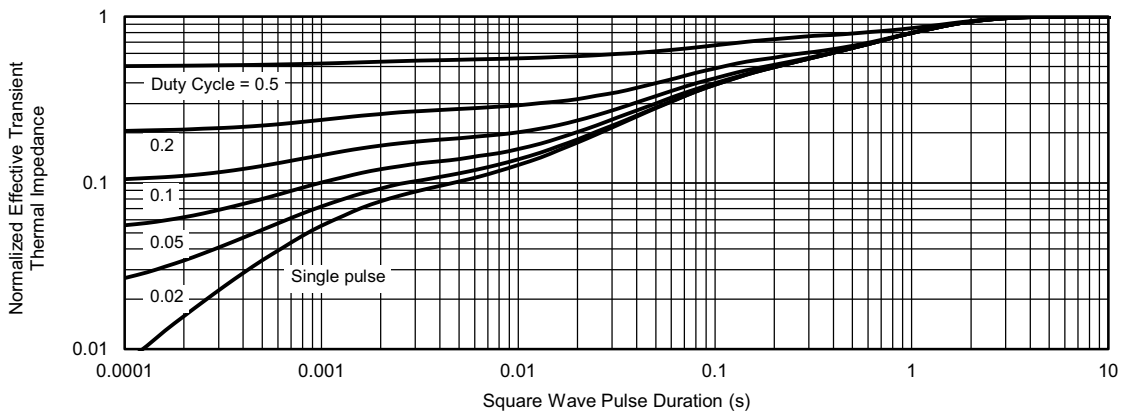
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a

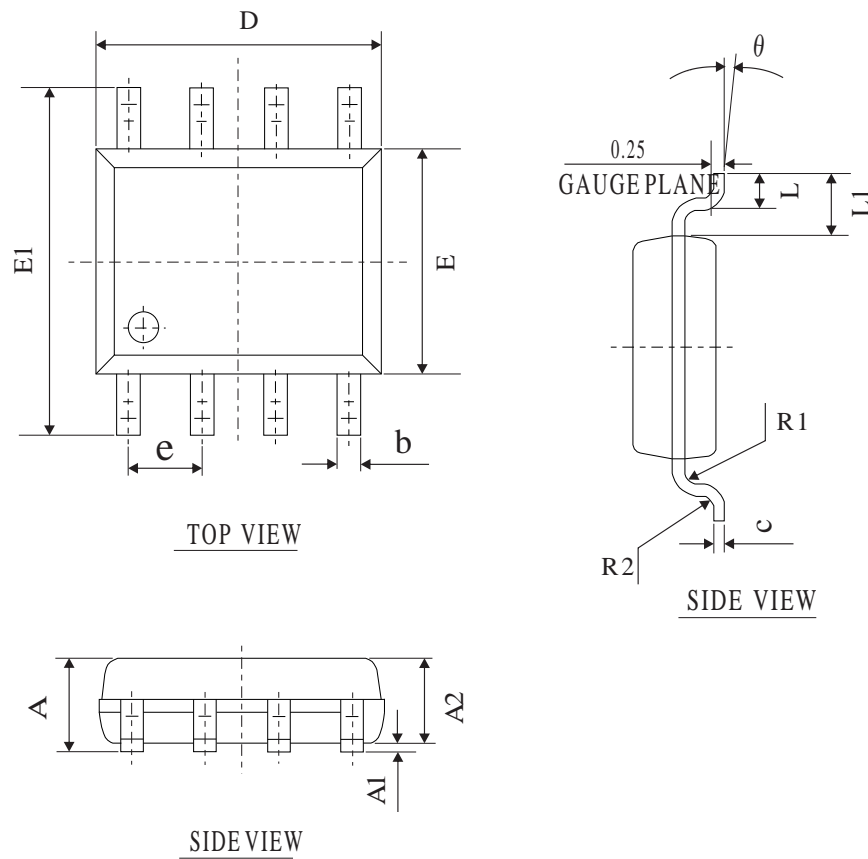


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

SOP-8 PACKAGE OUTLINE



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	1.30	1.60	1.85
A1	0.03	0.15	0.28
A2	1.20	1.45	1.70
b	0.26	0.40	0.54
C	0.132	0.203	0.273
D	4.50	4.90	5.30
E	3.50	3.00	4.30
E1	5.50	6.00	6.50
L	0.30	0.70	1.10
θ	2°	4°	6°
L1	1.04REF		
e	1.27BSC		
R1	0.07TYP		
R2	0.07TYP		

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